

1. Package Information



3. Packing Specification

3.1 Packing form, Quantity, PIN1 Orientation

l	iape&Ree
pcs] 1	1500
E	Ξ2
	pcs] 1



3.7 Tape and Reel Specification

3.7.1 Tape Dimension



3.7.2 Reel Dimension



3.8 Packing Method

1 reel(s) or less per unit box



4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

5. Marking Specification

		I			
					→ Production lot number
					\rightarrow Production week code
					→ Production year code
Stora	ge conditions				
6.1 S	torage environment				
	Recommended storag			11-14	
	Temperature	Min. 5	Max. 30	Unit °C	
	Humidity		30 70	% RH 📢	
				<u>,,,,,,</u>	
6.2 S	torage period				
		Min.	Max.	Unit	
	Storage period	-	1	year	
635	pecified storage perio	od until soldor			
0.5 5	pecilieu storage perio	Min.	Max.	Unit	9
	Acceptable time		168	hour	
	The above value is a ti	me from openir	ng the moisture	proof packag	ing until the soldering.
	Cases where it is nece				0
			ove-mentioned "		me"
	Case 2 : it ha	is passed more	e than a year no	t open	
	Recommended the dr	v process cond	litions	•	
			Temperature	[°C] T	īme [hour]
	Reel ^(Note1)		60		72
	Other Heat-proof co	ntainer	125		24
			ocess in a "Ree	l" state, the p	peelback strength will change.
	Please refer to the fol				
		Mir			nit
	Peelback strength	0.2	2 0.9	Ν	N
	The drying process is	the impact on t	the solderability	here lee the	e oxidation of the terminal portion
	will occur. Therefore, s		•		•
		poony the max			
	Recommended execut	tion count of th	e dry process		5

	Min.	Max.	Unit
Execution count	-	2	times

7. Soldering conditions

7.1 Recommended temperature profile for reflow





- 7.4.1 For mounting on flexible film
 - Mounting on flexible film, film bend may occur lack of lead from package, usage of support board and under fill is recommended.



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